

**IN THE SPECIFICATION**

**Please insert the following paragraph on page 1 after the title:**

**CROSS REFERENCE TO RELATED APPLICATIONS**

This patent application is related to U.S. Patent Application Serial Number \_\_\_\_\_ (Attorney Docket No. 303.884US1), entitled METHOD AND SYSTEM FOR CORRELATING AND COMBINING PRODUCTION AND NON-PRODUCTION DATA FOR ANALYSIS, to Naoki Toyoshima, Shinichi Murakami and Yuko Maeda, assigned to Micron Technology, Inc., and incorporated herein by reference.

**Please amend the paragraph beginning at page 13, line 15 as follows:**

FIG. 6A and FIG. 6B depict vertical furnace operations. Vertical furnace operations are part of process 110 in an embodiment. In a vertical furnace operation a pilot wafer 601 is used to monitor film thickness. It would be useful if this pilot wafer data could be gathered and stored with production data. Pilot wafers 601 may be used between single lots of production wafers 610, between multiple lots of production wafers 610. If a pilot wafer 601 is inserted into the space between lots, as depicted in FIG. 6A, the calculation of the lot data can be given by the following calculation:

$$V_i = \frac{(P_i + P_{i+1})}{2}$$

where,  $V_i$  is the calculated pilot wafer data,  $P_i$  is the measured pilot wafer data and  $P_{i+1}$  is the next measured pilot wafer data. If a pilot wafer 601 is placed at the top, center and bottom of all processed lots, as depicted in FIG. 6B, the lot data can be given by the following equations:

$$V_1 = \frac{P_1 + P_2}{2}$$

$$V_2 = \frac{P_1 + P_2}{2}$$

$$V_3 = P_2$$

$$V_4 = \frac{P_2 + P_3}{2}$$

$$V_5 = \frac{P_2 + P_3}{2}$$

where,  $V_1 \sim V_5$  are the calculated pilot wafer data and  $P_1 \sim P_3$  are the measured pilot wafer data. Pilot wafers **601** may also be used at some other interval to determine film thickness. In an embodiment, an average of pilot wafer readings before and after processing of a single lot is completed is used. In an embodiment, the first pilot wafer reading made some time after the completion of the processing of the production wafer lots is averaged with the first pilot wafer reading made some time before the processing of the production wafer lot is begun. In an embodiment, the pilot wafer reading made during the processing of lot is used as the pilot wafer data for that production wafer lot.